



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.020mm	3.5	
3	Top Layer	Copper	0.040mm		
4	Dielectric 2	PP-2116	0.110mm	4.1	
5	Layer 2	Copper	0.035mm		
6	Dielectric 1	FR-4	1.200mm	4.5	
7	Layer 3	Copper	0.035mm		
8	Dielectric 3	PP-2116	0.110mm	4.1	
9	Bottom Layer	Copper	0.040mm		
10	Bottom Solder	Solder Resist	0.020mm	3.5	
11	Bottom Overlay				

#### PCB NOTES

1. Number of layers - 4
2. Board size - 80mm x 58mm. Tolerance - +/- 0.1mm
3. Board thickness - 1.6mm +/-10%
4. Material - FR-4 High Tg, cooper thickness is 35um (1oz)
5. Solder Mask - Two sides, Green, Liquid. Solder mask mis-registration +/-0.025mm. No overlap permitted on SMD lands. Solder Mask is in accordance with IPC-SM-840 D, Class H
6. Silkscreen - TOP side only
7. Type of coating - ENIG
8. Electrical Test on both sides
9. Min dia of plated hole - 0.3mm
10. Min annular ring - 0.15mm
11. Min trace width - 0.2mm
12. Min clearance - 0.2mm
13. Non-functional pads (NFP) must be removed
14. Impedance control - No
15. For high-volume manufacturing internal layers 2 and 3 can be removed completely